



## SSC8164GS8

### N-Channel Small Switching MOSFET with ESD Protection

#### ➤ Features

$V_{DS}$	$V_{GS}$	$R_{DS(ON)}$ Typ.	$I_D$	ESD
60V	$\pm 20V$	$1\Omega @ 10V$	0.4A	500V
		$1.5\Omega @ 4.5V$		

#### ➤ Description

This device is an N-Channel enhancement mode MOSFET, with low on-resistance, fast switching speed and low threshold voltage, it is ideal for portable equipment.

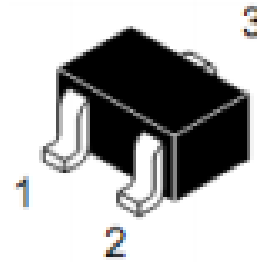
#### ➤ Applications

- Direct Logic-Level Interface: TTL/CMOS
- Drivers: Relays, Solenoids, Lamps, Hammers
- Display, Memories, Transistors, etc.
- Battery Operated System
- Solid-State Relays

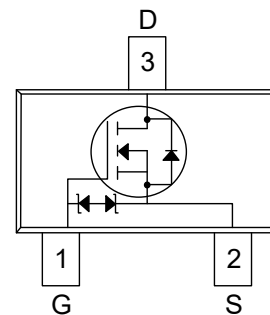
#### ➤ Ordering Information

Device	Package	Shipping
SSC8164GS8	SOT-523	3000/Reel

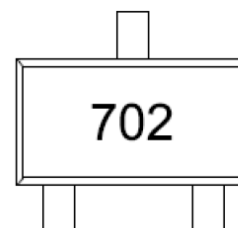
#### ➤ Pin configuration



**SOT-523**



**Pin Configuration (Top View)**



**Marking**



➤ **Absolute Maximum Ratings ( $T_A=25^{\circ}\text{C}$  unless otherwise noted)**

Symbol	Parameter	Ratings	Unit
$V_{\text{DSS}}$	Drain-to-Source Voltage	60	V
$V_{\text{GSS}}$	Gate-to-Source Voltage	$\pm 20$	V
$I_{\text{D}}$	Continuous Drain Current <sup>a</sup>	0.4	A
$I_{\text{DM}}$	Pulsed Drain Current <sup>b</sup>	1	A
$P_{\text{D}}$	Power Dissipation <sup>c</sup>	0.8	W
$P_{\text{DSM}}$	Power Dissipation <sup>a</sup>	0.3	W
$T_{\text{J}}$	Operation junction temperature	$-55\sim 150$	$^{\circ}\text{C}$
$T_{\text{STG}}$	Storage temperature range	$-55\sim 150$	$^{\circ}\text{C}$

➤ **Thermal Resistance Ratings ( $T_A=25^{\circ}\text{C}$  unless otherwise noted)**

Symbol	Parameter	Maximum	Unit
$R_{\theta\text{JA}}$	Junction-to-Ambient Thermal Resistance <sup>a</sup>	430	$^{\circ}\text{C}/\text{W}$
$R_{\theta\text{JC}}$	Junction-to-Case Thermal Resistance	160	$^{\circ}\text{C}/\text{W}$

Note:

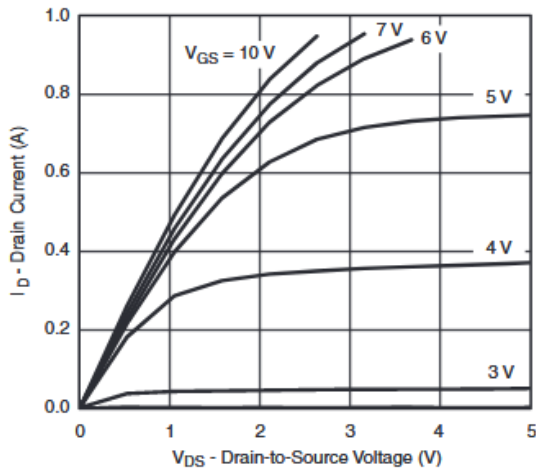
- The value of  $R_{\theta\text{JA}}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz.copper, in a still air environment with  $T_A=25^{\circ}\text{C}$ . The value in any given application depends on the user is specific board design. The power dissipation is based on the  $t\leq 10\text{s}$  thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The power dissipation  $P_{\text{D}}$  is based on  $T_{\text{J(MAX)}}=150^{\circ}\text{C}$ , using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.

**➤ Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)**

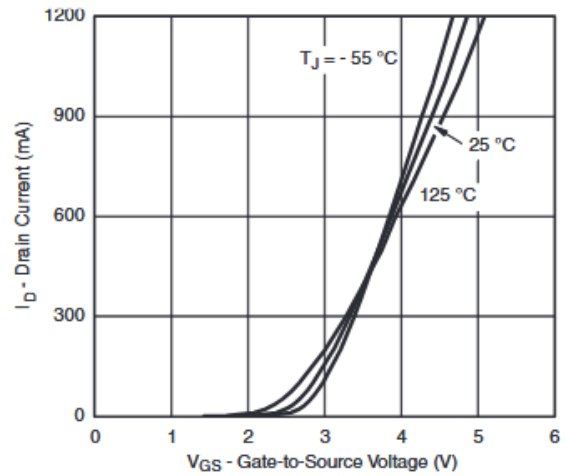
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	60			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	0.75	1	1.25	V
Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 0.5A		1	2.5	Ω
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 0.5A		1.5	3.5	
		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 0.2A		2.8	4	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 60V, V <sub>GS</sub> = 0V			1	μA
Gate-Source Leak Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±15V, V <sub>DS</sub> = 0V			±10	μA
Transconductance	G <sub>FS</sub>	V <sub>DS</sub> = 10V, I <sub>D</sub> = 0.2A		0.1		s
Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> = 0.2A			1.3	V
Input Capacitance	C <sub>ISS</sub>	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V, f = 1MHz		30		pF
Output Capacitance	C <sub>OSS</sub>			6		
Reverse Transfer Capacitance	C <sub>RSS</sub>			2.9		
Turn-on Delay Time	T <sub>D(ON)</sub>	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 10V, I <sub>D</sub> = 100mA		25		ns
Rise Time	T <sub>r</sub>			10		
Turn-off Delay Time	T <sub>D(OFF)</sub>			35		
Turn-off delay time	T <sub>f</sub>			20		
Total Gate Charge	Q <sub>G</sub>	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 15V, I <sub>D</sub> = 0.2A		0.4		nC
Gate Source Charge	Q <sub>GS</sub>			0.1		
Gate Drain Charge	Q <sub>GD</sub>			0.11		



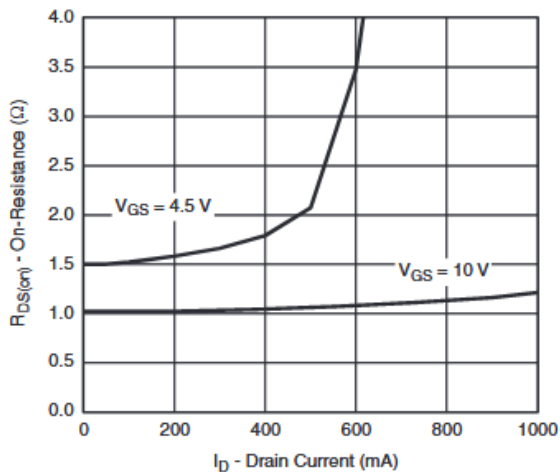
➤ **Typical Performance Characteristics ( $T_A=25^\circ\text{C}$  unless otherwise noted)**



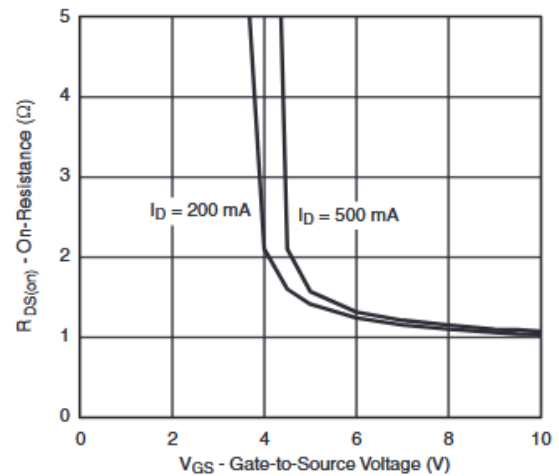
**Output Characteristics**



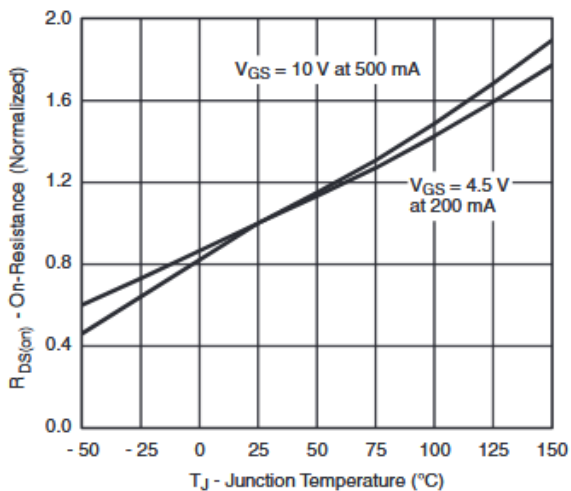
**Transfer Characteristics**



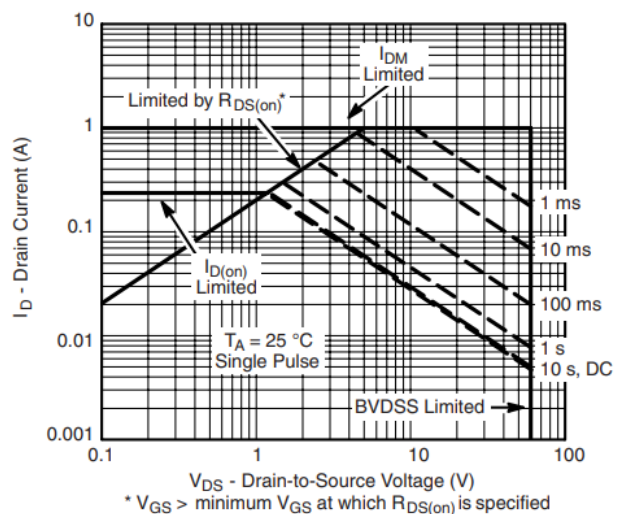
**On-Resistance vs. Drain Current**



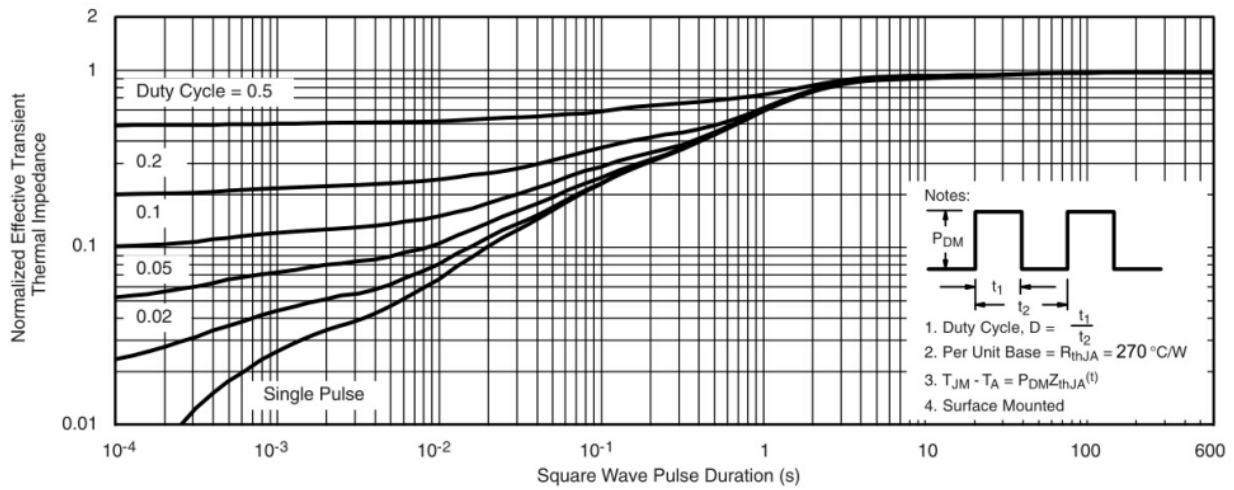
**On-Resistance vs. Gate-Source Voltage**



**On-Resistance vs. Junction Temperature**

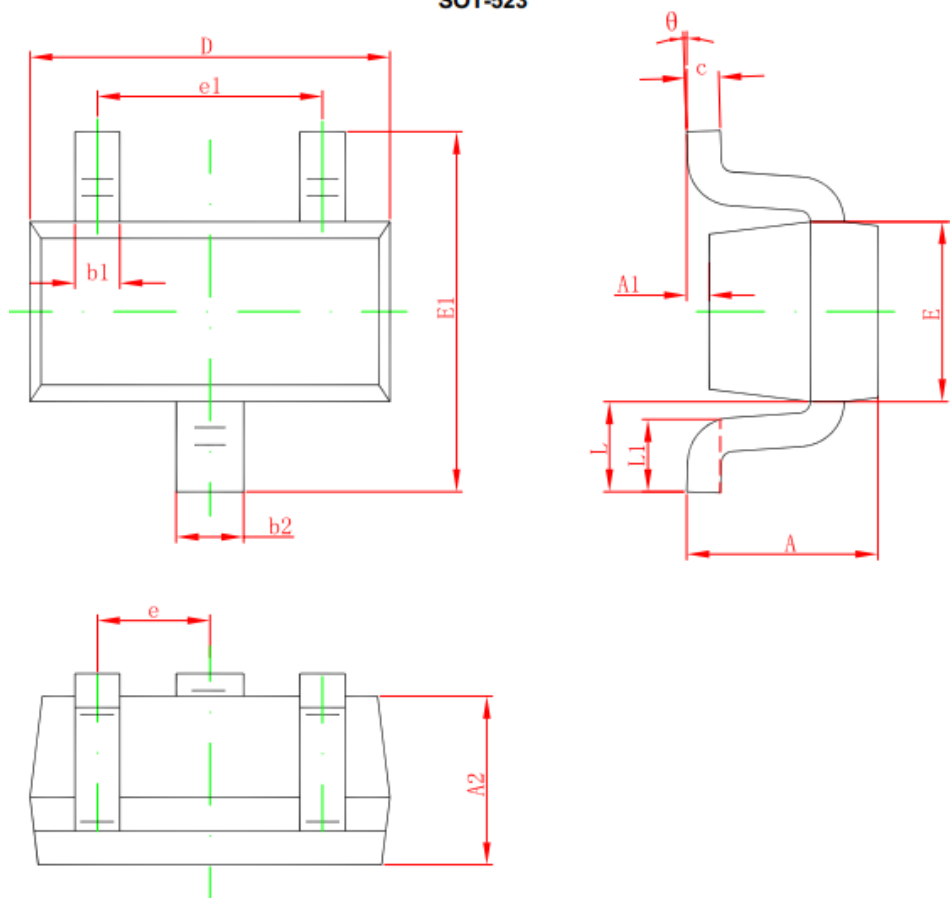


**Safe Operating Area**



## ➤ Package Information

SOT-523



Symbol	Dimension in Millimeters	
	Min.	Max.
A	0.700	0.900
A1	0.000	0.100
A2	0.700	0.800
b1	0.150	0.250
b2	0.250	0.350
c	0.100	0.200
D	1.500	1.700
E	0.700	0.900
E1	1.450	1.750
e	0.500 Typ.	
e1	0.900	1.100
L	0.400 Ref.	
L1	0.260	0.460
θ	0°	8°



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